

Size: **60 x 120 mm**

Thickness: **1,6 mm**

Weight: **29 g**

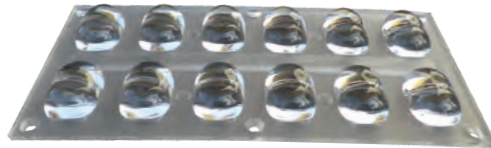
Electricity Line: **Copper**

Thickness of copper: **35um**

Thickness of the dielectric: **70um**

Thickness of the aluminum-base: **1.5mm**

Lenses for PCB 724-99:



12 B ST 13060 XP

The result of the test:

Item	Test item	Technology request	Unit	Test result	
1	Peel Strength	A	≥1.8	N/mm	2.0
	After thermal stress (260°C)		≥1.8	N/mm	1.8
2	Blister test After Thermal stress (288°C , 2min)	288°C, 2 min No delaminating	/	Ok	
3	Thermal resistance		≤2.0	°C/W	1.0
4	Thermal-Conductive Factor			W/m-k	1.0
5	Flammability(A)		FV-O	/	FV-O
6	Surface Resistivity	A	≥ 1×10 ⁵	MΩ	5×10 ⁷
	Constant humidity treatment (90%,35°C,96h)		≥ 1×10 ⁵	MΩ	2×10 ⁶
7	Volume Resistivity	A	≥ 1×10 ⁶	MΩ-m	4×10 ⁸
	Constant humidity treatment (90%,35°C,96h)		≥ 1×10 ⁶	MΩ-m	5×10 ⁷
8	Dielectric Breakdown(DC)		≥ 28.5	KV/MM	31
9	Dielectric constant(1MHz) (40°C, 93%, 96h)		≤4.4	/	4.2
10	Dielectric dissipation factor (1MHz) (40°C , 93% , 96h)		≤0.03	/	0.02

